



# CGD944C

870 MHz, 25 dB gain power doubler amplifier

Rev. 4 — 25 June 2014

Product data sheet

## 1. Product profile

### 1.1 General description

Hybrid amplifier module in a SOT115J package, operating at a supply voltage of 24 V (DC), employing Hetero Field Effect Transistor (HFET) GaAs dies.

### 1.2 Features and benefits

- High output capability
- Excellent linearity
- Extremely low noise
- Excellent return loss properties
- Rugged construction
- Gold metallization ensures excellent reliability

### 1.3 Applications

- CATV systems operating in the 40 MHz to 870 MHz frequency range

### 1.4 Quick reference data

Table 1. Quick reference data

| Symbol           | Parameter     | Conditions               | Min | Typ | Max | Unit |
|------------------|---------------|--------------------------|-----|-----|-----|------|
| $G_p$            | power gain    | $f = 870 \text{ MHz}$    | 24  | 25  | 26  | dB   |
| $I_{\text{tot}}$ | total current | $V_B = 24 \text{ V}$ [1] | -   | 450 | -   | mA   |

[1] Direct Current (DC).

## 2. Pinning information

Table 2. Pinning

| Pin  | Description | Simplified outline | Graphic symbol |
|------|-------------|--------------------|----------------|
| 1    | input       |                    |                |
| 2, 3 | common      |                    |                |
| 5    | + $V_B$     |                    |                |
| 7, 8 | common      |                    |                |
| 9    | output      |                    |                |



### 3. Ordering information

Table 3. Ordering information

| Type number | Package |  | Version |
|-------------|---------|--|---------|
|             | Name    | Description  |         |
| CGD944C     | -       | rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads | SOT115J |

### 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol      | Parameter                 | Conditions        | Min | Max  | Unit |
|-------------|---------------------------|-------------------|-----|------|------|
| $V_B$       | supply voltage            |                   | -   | 30   | V    |
| $V_{i(RF)}$ | RF input voltage          | single tone       | -   | 75   | dBmV |
|             |                           | 132 channels flat | -   | 45   | dBmV |
| $T_{stg}$   | storage temperature       |                   | -40 | +100 | °C   |
| $T_{mb}$    | mounting base temperature |                   | -20 | +100 | °C   |

### 5. Characteristics

Table 5. Characteristics

Bandwidth to 870 MHz;  $V_B = 24$  V (DC);  $T_{mb} = 35$  °C; unless otherwise specified.

| Symbol     | Parameter                         | Conditions                 | Min | Typ | Max | Unit |     |
|------------|-----------------------------------|----------------------------|-----|-----|-----|------|-----|
| $G_p$      | power gain                        | $f = 870$ MHz              | 24  | 25  | 26  | dB   |     |
| $SL_{sl}$  | slope straight line               | $f = 40$ MHz to 870 MHz    | [1] | 1   | -   | 2    | dB  |
| FL         | flatness of frequency response    | $f = 40$ MHz to 870 MHz    | [2] | -   | 0.5 | -    | dB  |
| CTB        | composite triple beat             | 79 + 53 flat NTSC channels | [3] | -   | -68 | -66  | dBc |
|            |                                   | 98 flat PAL channels       | [4] | -   | -66 | -    | dBc |
| CSO        | composite second-order distortion | 79 + 53 flat NTSC channels | [3] | -   | -70 | -67  | dBc |
|            |                                   | 98 flat PAL channels       | [4] | -   | -66 | -    | dBc |
| Xmod       | cross modulation                  | 79 + 53 flat NTSC channels | [3] | -   | -66 | -58  | dB  |
| $RL_{in}$  | input return loss                 | $f = 40$ MHz to 80 MHz     | 20  | -   | -   | dB   |     |
|            |                                   | $f = 80$ MHz to 160 MHz    | 19  | -   | -   | dB   |     |
|            |                                   | $f = 160$ MHz to 320 MHz   | 18  | -   | -   | dB   |     |
|            |                                   | $f = 320$ MHz to 640 MHz   | 18  | -   | -   | dB   |     |
|            |                                   | $f = 640$ MHz to 870 MHz   | 18  | -   | -   | dB   |     |
| $RL_{out}$ | output return loss                | $f = 40$ MHz to 80 MHz     | 20  | -   | -   | dB   |     |
|            |                                   | $f = 80$ MHz to 160 MHz    | 19  | -   | -   | dB   |     |
|            |                                   | $f = 160$ MHz to 320 MHz   | 18  | -   | -   | dB   |     |
|            |                                   | $f = 320$ MHz to 640 MHz   | 18  | -   | -   | dB   |     |
|            |                                   | $f = 640$ MHz to 870 MHz   | 18  | -   | -   | dB   |     |

**Table 5. Characteristics ...continued**Bandwidth to 870 MHz;  $V_B = 24\text{ V (DC)}$ ;  $T_{mb} = 35\text{ °C}$ ; unless otherwise specified.

| Symbol    | Parameter     | Conditions              | Min | Typ | Max | Unit |
|-----------|---------------|-------------------------|-----|-----|-----|------|
| NF        | noise figure  | f = 50 MHz              | -   | 3.5 | 5.0 | dB   |
|           |               | f = 870 MHz             | -   | 3.5 | 5.0 | dB   |
| $I_{tot}$ | total current | $V_B = 24\text{ V}$ [5] | -   | 450 | -   | mA   |

[1]  $G_p$  at 870 MHz minus  $G_p$  at 40 MHz.

[2] flatness straight line (peak to valley).

[3] 79 NTSC channels (5.25 MHz to 547.25 MHz, 48 dBmV output level) + 53 NTSC channels (553.25 MHz to 870 MHz, 38 dBmV output level).

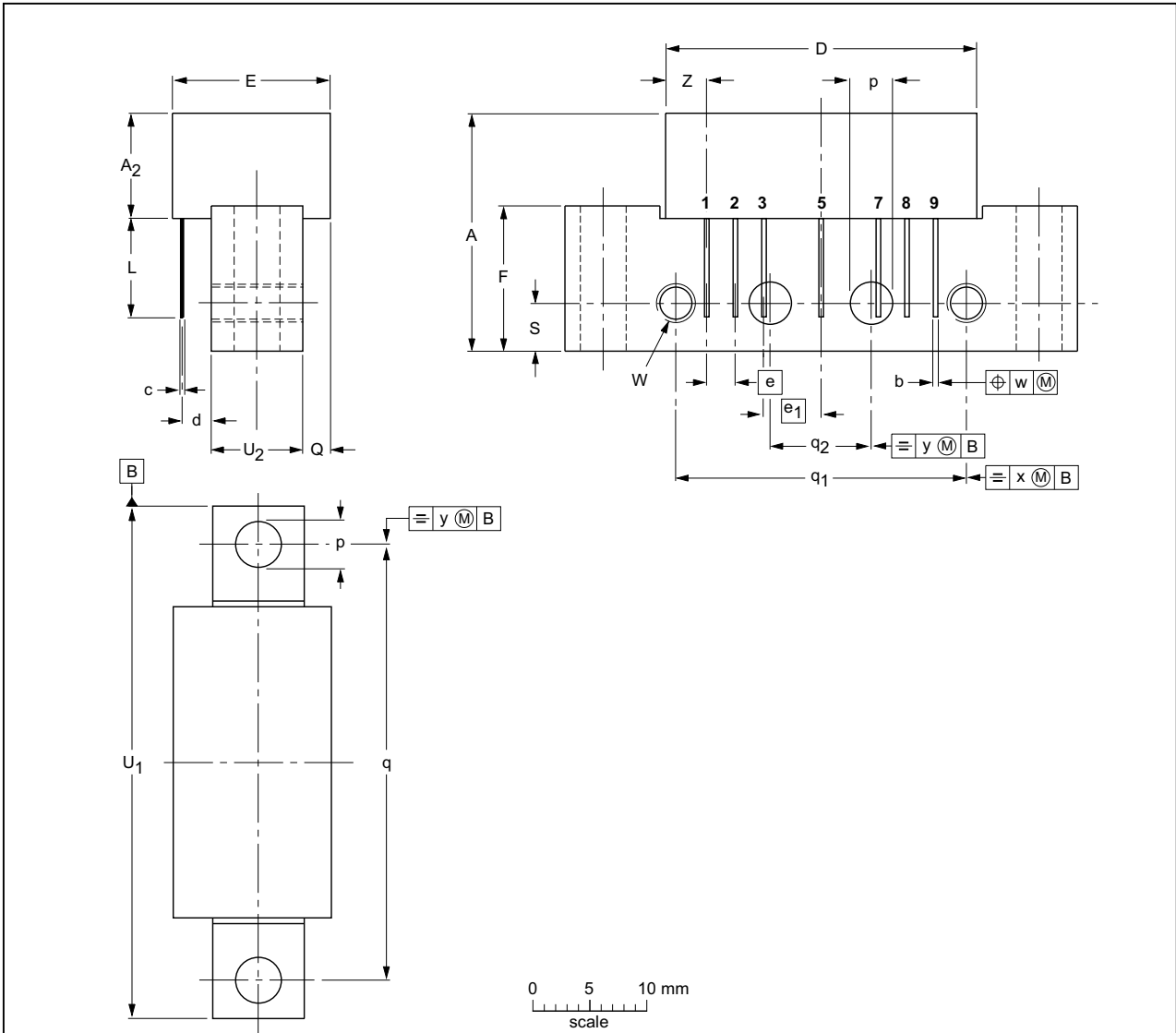
[4]  $V_o = 48\text{ dBmV}$ .

[5] Direct Current (DC).

6. Package outline

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads

SOT115J



DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A <sub>2</sub> max. | b            | c    | D max. | d            | E max. | e    | e <sub>1</sub> | F    | L min. | p            | Q max. | q    | q <sub>1</sub> | q <sub>2</sub> | S   | U <sub>1</sub> | U <sub>2</sub> | W           | w    | x   | y   | Z max. |
|------|--------|---------------------|--------------|------|--------|--------------|--------|------|----------------|------|--------|--------------|--------|------|----------------|----------------|-----|----------------|----------------|-------------|------|-----|-----|--------|
| mm   | 20.8   | 9.5                 | 0.51<br>0.38 | 0.25 | 27.2   | 2.04<br>2.54 | 13.75  | 2.54 | 5.08           | 12.7 | 8.8    | 4.15<br>3.85 | 2.4    | 38.1 | 25.4           | 10.2           | 4.2 | 44.75<br>44.25 | 8.2<br>7.8     | 6-32<br>UNC | 0.25 | 0.7 | 0.1 | 3.8    |

| OUTLINE VERSION | REFERENCES |       |       | EUROPEAN PROJECTION | ISSUE DATE            |
|-----------------|------------|-------|-------|---------------------|-----------------------|
|                 | IEC        | JEDEC | JEITA |                     |                       |
| SOT115J         |            |       |       |                     | -04-02-04<br>10-06-18 |

Fig 1. Package outline SOT115J

## 7. Handling information

### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

## 8. Abbreviations

Table 6. Abbreviations

| Acronym | Description                            |
|---------|--|
| CATV    | Community Antenna TeleVision           |
| DC      | Direct Current                         |
| GaAs    | Gallium-Arsenide                       |
| NTSC    | National Television Standard Committee |
| PAL     | Phase-Alternation Line                 |
| RF      | Radio Frequency                        |
| UNC     | UNified Coarse thread                  |

## 9. Revision history

Table 7. Revision history

| Document ID    | Release date   | Data sheet status  | Change notice | Supersedes  |
|----------------|--|--------------------|---------------|-------------|
| CGD944C v.4    | 20140625   | Product data sheet | -             | CGD944C v.3 |
| Modifications: | <ul style="list-style-type: none"> <li>• <a href="#">Table note 3 on page 3</a>: 997.25 MHz has been changed to 870 MHz.</li> <li>• <a href="#">Section 7 on page 5</a>: The ESD warning has been moved here from the front page.</li> <li>• Legal texts have been updated.</li> </ul> |                    |               |             |
| CGD944C v.3    | 20100929   | Product data sheet | -             | CGD944C v.2 |
| CGD944C v.2    | 20091116   | Product data sheet | -             | CGD944C v.1 |
| CGD944C v.1    | 20070606   | Product data sheet | -             | -           |

## 10. Legal information

### 10.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

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## 12. Contents

|           |                                       |          |
|-----------|---------------------------------------|----------|
| <b>1</b>  | <b>Product profile</b> . . . . .      | <b>1</b> |
| 1.1       | General description . . . . .         | 1        |
| 1.2       | Features and benefits . . . . .       | 1        |
| 1.3       | Applications . . . . .                | 1        |
| 1.4       | Quick reference data . . . . .        | 1        |
| <b>2</b>  | <b>Pinning information</b> . . . . .  | <b>1</b> |
| <b>3</b>  | <b>Ordering information</b> . . . . . | <b>2</b> |
| <b>4</b>  | <b>Limiting values</b> . . . . .      | <b>2</b> |
| <b>5</b>  | <b>Characteristics</b> . . . . .      | <b>2</b> |
| <b>6</b>  | <b>Package outline</b> . . . . .      | <b>4</b> |
| <b>7</b>  | <b>Handling information</b> . . . . . | <b>5</b> |
| <b>8</b>  | <b>Abbreviations</b> . . . . .        | <b>5</b> |
| <b>9</b>  | <b>Revision history</b> . . . . .     | <b>5</b> |
| <b>10</b> | <b>Legal information</b> . . . . .    | <b>6</b> |
| 10.1      | Data sheet status . . . . .           | 6        |
| 10.2      | Definitions . . . . .                 | 6        |
| 10.3      | Disclaimers . . . . .                 | 6        |
| 10.4      | Trademarks . . . . .                  | 7        |
| <b>11</b> | <b>Contact information</b> . . . . .  | <b>7</b> |
| <b>12</b> | <b>Contents</b> . . . . .             | <b>8</b> |

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